

Title of Change:	Revision of Case Outline 507BA
Effective date:	05 Jul 2024
Contact information:	Contact your local onsemi Sales Office or saziela.senin@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Datasheet/Product Doc change

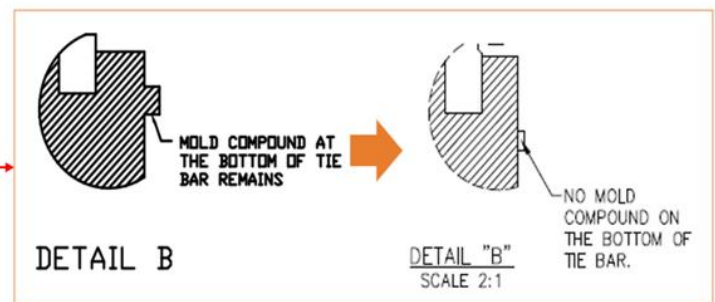
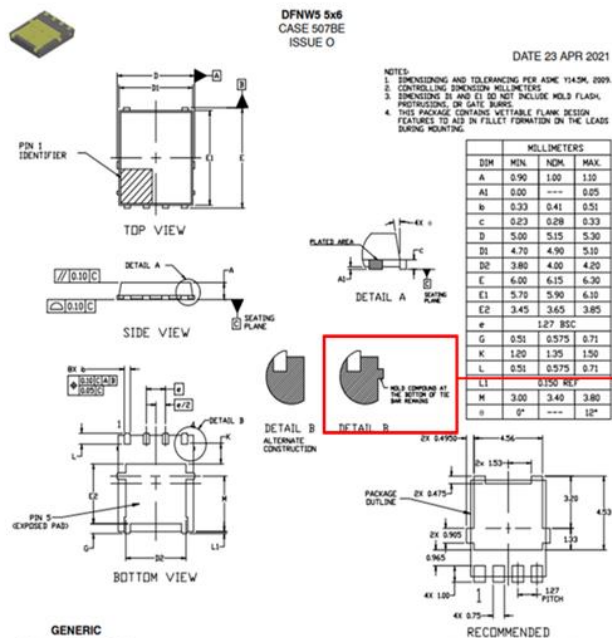
Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Seremban, Malaysia	None

Description and Purpose:

This Product Bulletin is to advise customers of a change to detail B in case outline from “Mold compound at the bottom of tie bar remains” to “No mold compound at the bottom of the tie bar” for case 507BE. No change to solder footprint is required. There is no material, dimension or manufacturing change.

**MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS**



List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

NTMFWS1D5N08XT1G	
------------------	--